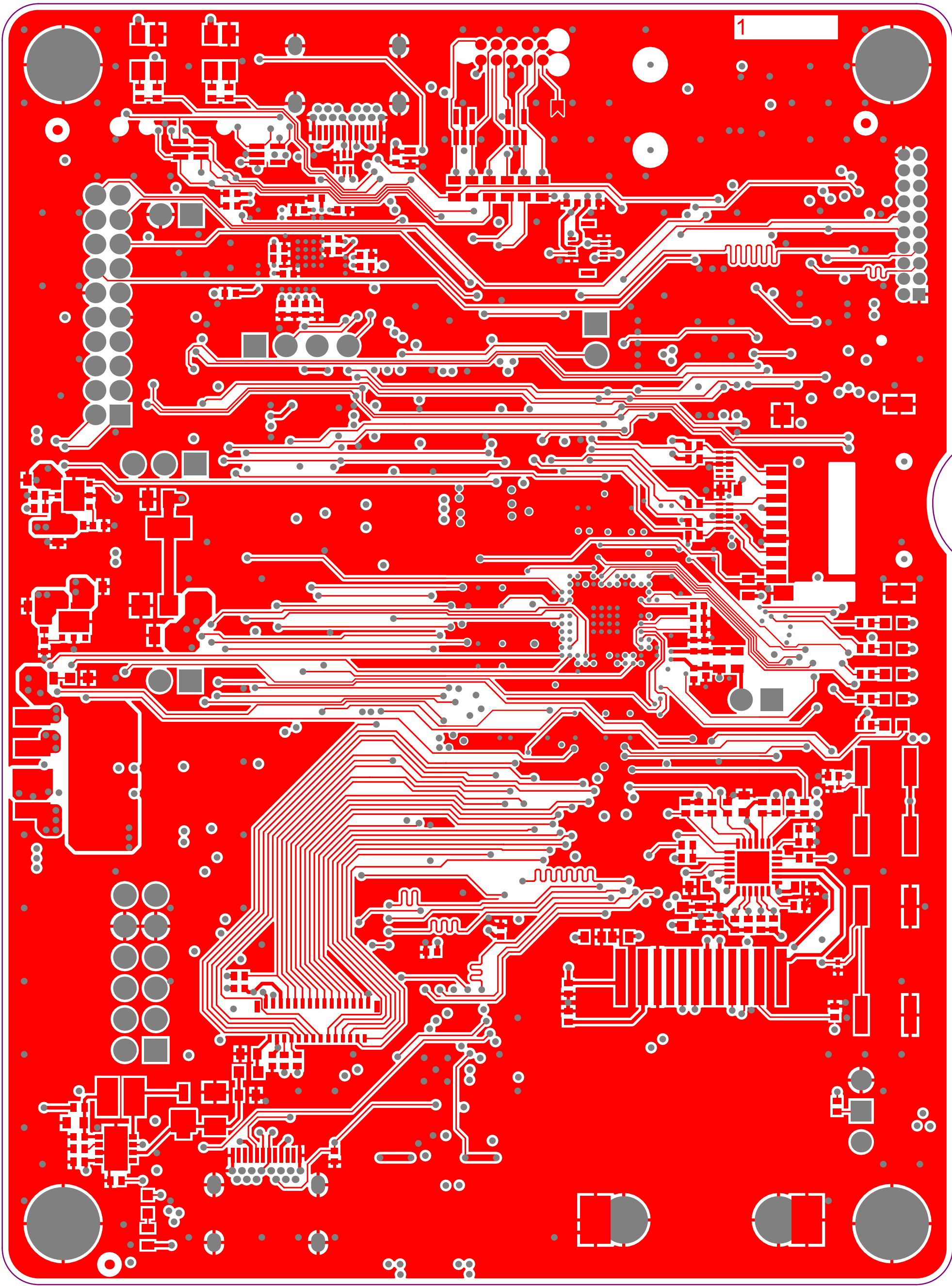
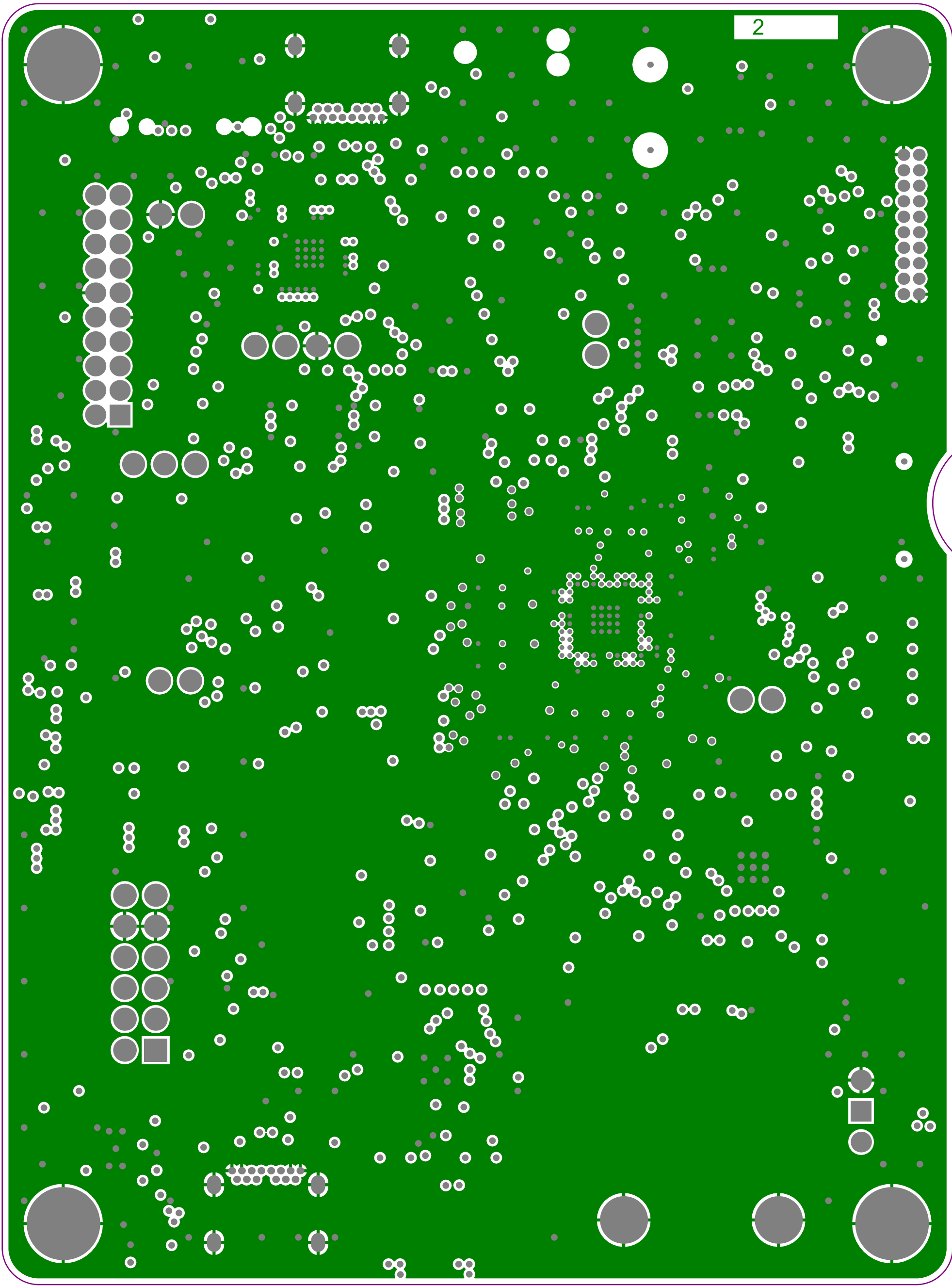
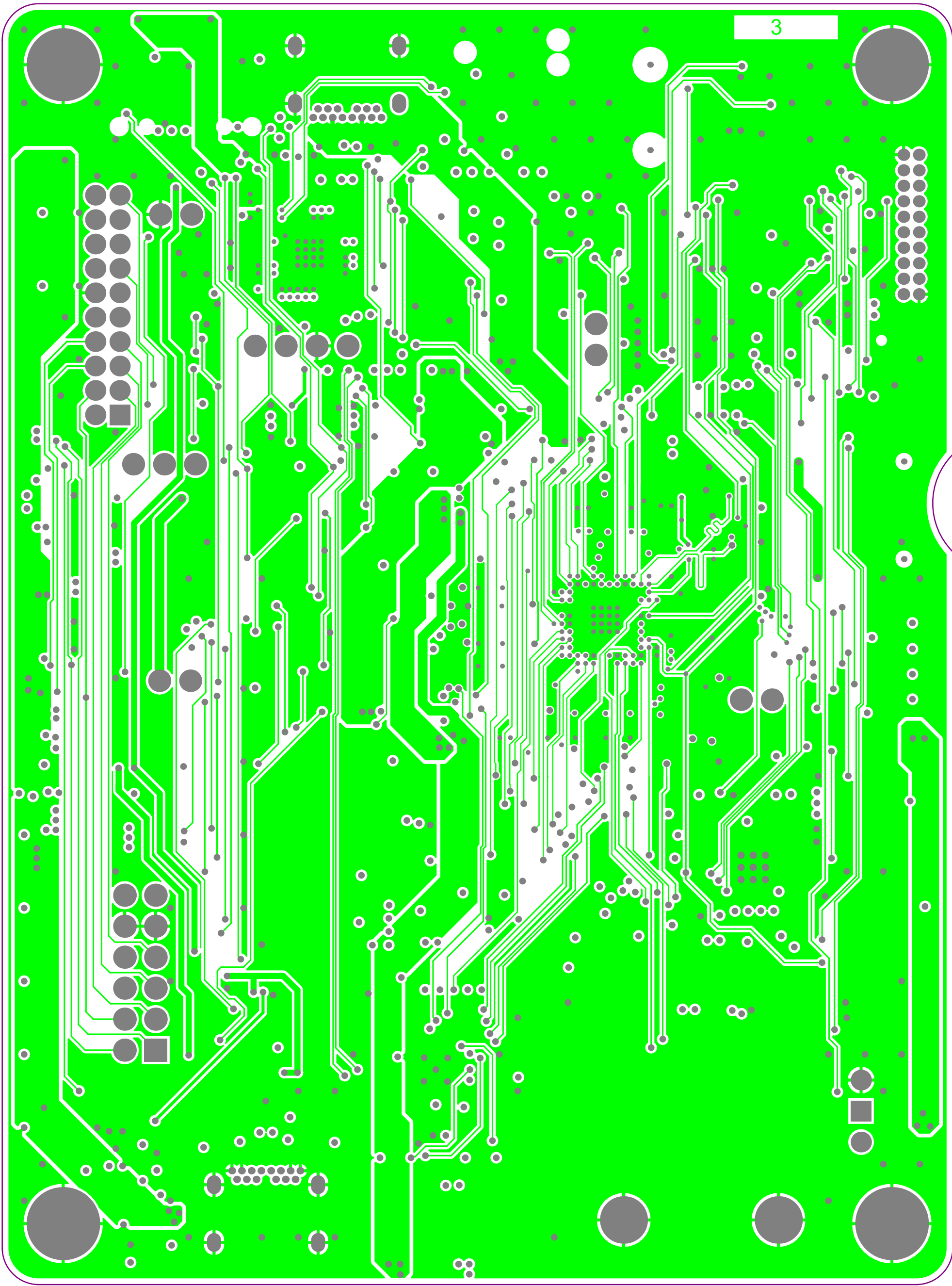
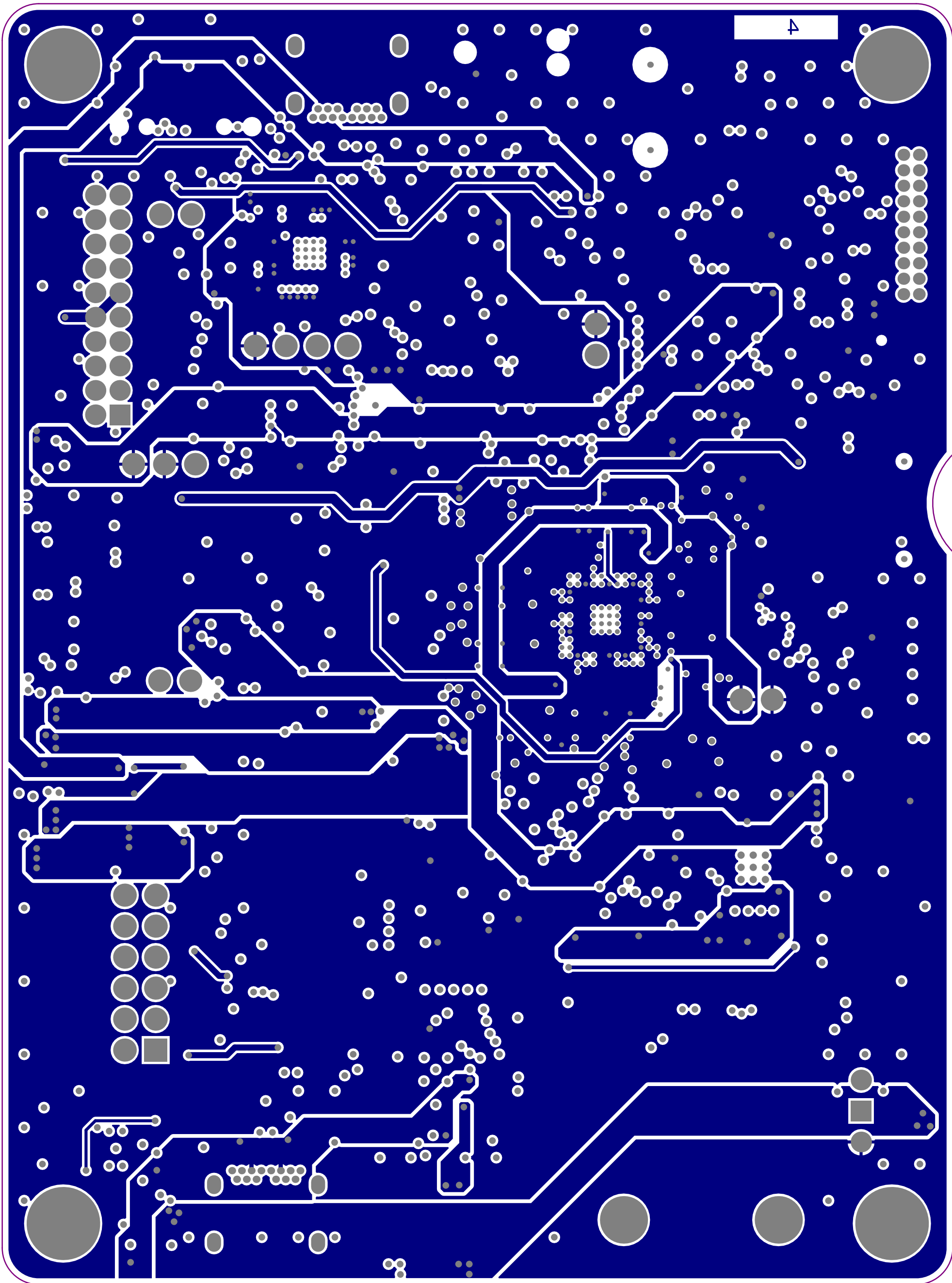


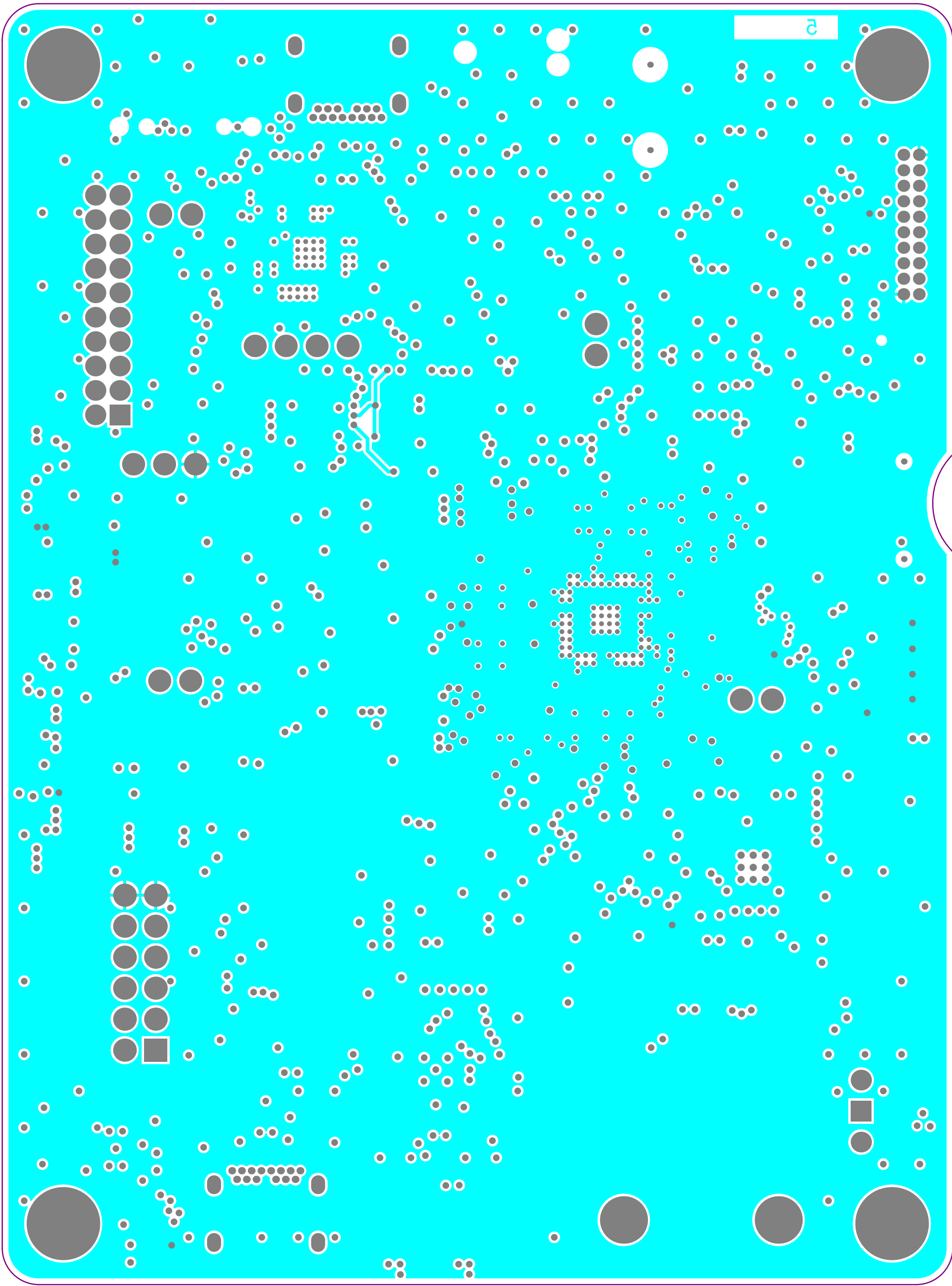
.GTS





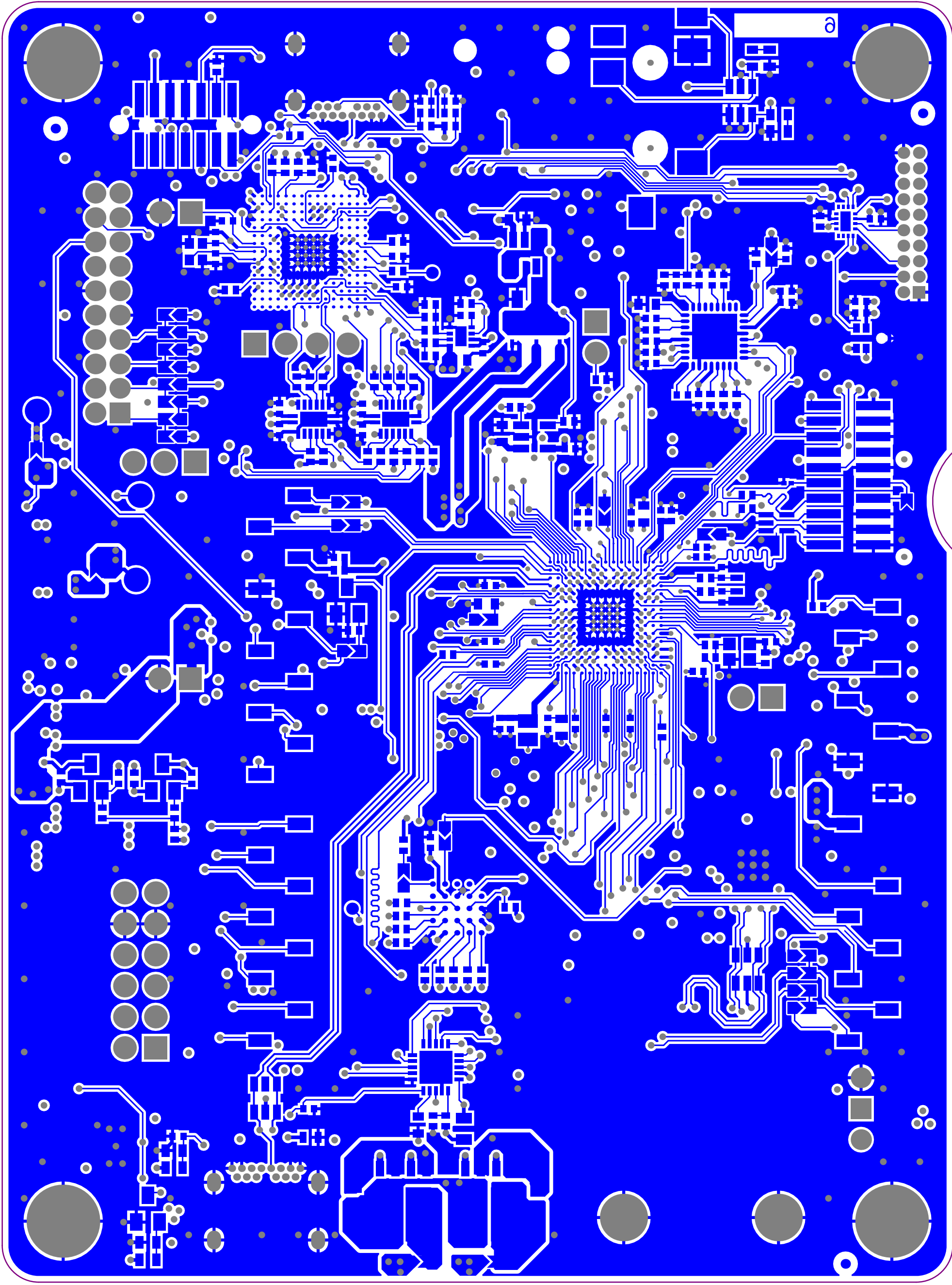


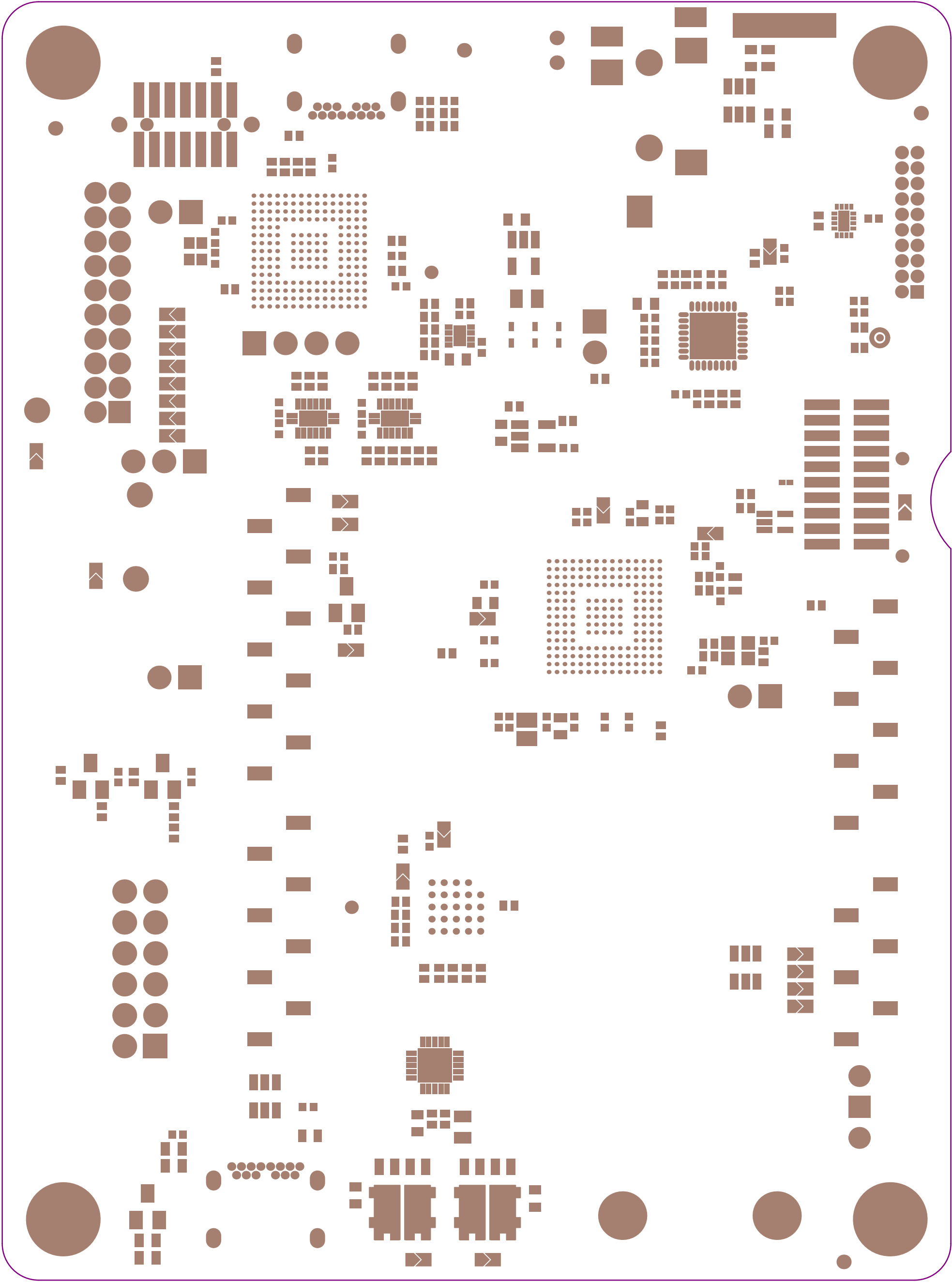




.GBL

Bottom Layer







PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☐ TG-170

☒ TG-150

☐ TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☐ GREEN

☐ WHITE

☒ BLUE

☐ BLACK

D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK

☐ Blue ink PANTONE 2955

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

F. IMPEDANCE CONTROL :

☐ NO

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK

☐ NON-CONDUCTIVE EPOXY.

H. STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

PCB : TYPE 3

ASPECT-RATIO, AXE Z :

6:1 to 8:1

LEVEL "B"

MINIMUM PARAMETERS

DEFAULT

TRACKS : 0.1mm

GAPS : 0.09mm

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0,015mm	3,5	
1	Top Layer	Copper	0,042mm		
	Dielectric 1		0,100mm	4,2	
2	Signal Layer 1	Copper	0,035mm		
	Dielectric 2		0,102mm	4,2	
3	Signal Layer 2	Copper	0,035mm		
	Dielectric 3		0,946mm	4,2	
4	Signal Layer 3	Copper	0,035mm		
	Dielectric 4		0,102mm	4,2	
5	Signal Layer 4	Copper	0,035mm		
	Dielectric 5		0,100mm	4,2	
6	Bottom Layer	Copper	0,042mm		
	Bottom Solder	Solder Resist	0,015mm	3,5	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
■	1	0,500mm (19,69mil)	NPTH	Round	Top Layer - Bottom Layer	Pad
⊠	2	0,970mm (38,19mil)	NPTH	Round	Top Layer - Bottom Layer	Pad
G	2	1,000mm (39,37mil)	NPTH	Round	Top Layer - Bottom Layer	Pad
▽	2	1,190mm (46,85mil)	NPTH	Round	Top Layer - Bottom Layer	Pad
D	2	2,000mm (78,74mil)	NPTH	Round	Top Layer - Bottom Layer	Pad
◇	2	3,250mm (127,95mil)	PTH	Round	Top Layer - Bottom Layer	Pad
✕	3	1,100mm (43,31mil)	NPTH	Round	Top Layer - Bottom Layer	Pad
☆	4	3,500mm (137,79mil)	PTH	Round	Top Layer - Bottom Layer	Pad
✕	8	0,450mm (17,72mil)	PTH	Slot	Top Layer - Bottom Layer	Pad
○	9	0,300mm (11,81mil)	PTH	Round	Top Layer - Bottom Layer	Via
E	12	1,100mm (43,31mil)	PTH	Round	Top Layer - Bottom Layer	Pad
⊠	15	1,000mm (39,37mil)	PTH	Round	Top Layer - Bottom Layer	Pad
Q	20	0,700mm (27,56mil)	PTH	Round	Top Layer - Bottom Layer	Pad
K	23	0,900mm (35,43mil)	PTH	Round	Top Layer - Bottom Layer	Pad
⊕	28	0,400mm (15,75mil)	PTH	Round	Top Layer - Bottom Layer	Pad
□	203	0,200mm (7,87mil)	PTH	Round	Top Layer - Bottom Layer	Via
L	762	0,350mm (13,78mil)	PTH	Round	Top Layer - Bottom Layer	Via
	1098 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

